ABSTRACT

INTEGRATED CIRCUIT SYSTEM EMPLOYING BACK END OF LINE VIA TECHNIQUES

An integrated circuit system that includes: providing a substrate including front-end-of-line circuitry; forming a first metallization layer over the substrate and electrically connected to the substrate; forming a viabar or a via group over the first metallization layer; and forming a second metallization layer over the first metallization layer and electrically connected to the first metallization layer through either the viabar or the via group.

Fig. 4